



APSEMI

AC3M0120065K
Silicon Carbide Power MOSFET
N-Channel Enhancement Mode

Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating ; RoHS compliant

Parameter	Rating	Units
V_{DS}	650	V
$I_D @ 25^\circ C$	23	A
$R_{DS(on)}$	120	$m\Omega$

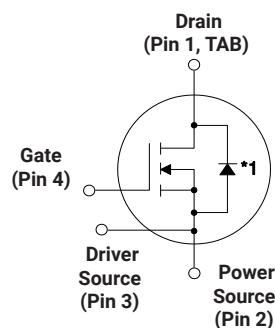


Applications

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating



TO-247-4
Package



- (1) Drain
(2) Power Source
(3) Driver Source
(4) Gate

*1 Body Diode

Inner circuit

Maximum Ratings

Symbol	Parameter	Value	Unit	Note
V_{DSS}	Drain - Source Voltage, $T_c = 25^\circ C$	650	V	
V_{GS}	Gate - Source voltage (Under transient events < 100 ns)	-8/+19	V	
I_D	Continuous Drain Current, $V_{GS} = 15 V$, $T_c = 25^\circ C$	23	A	
	Continuous Drain Current, $V_{GS} = 15 V$, $T_c = 100^\circ C$	18		
$I_{D(pulse)}$	Pulsed Drain Current, Pulse width t_p limited by T_{jmax}	50	A	
P_D	Power Dissipation, $T_c=25^\circ C$, $T_j = 175^\circ C$	97	W	
T_J , T_{stg}	Operating Junction and Storage Temperature	-40 to +175	°C	
T_L	Solder Temperature, 1.6mm (0.063") from case for 10s	260	°C	
M_d	Mounting Torque, (M3 or 6-32 screw)	1 8.8	Nm lbf-in	



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Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	650			V	$V_{\text{GS}} = 0 \text{ V}, I_D = 100 \mu\text{A}$	
V_{Gson}	Gate-Source Recommended Turn-On Voltage		15		V		
V_{Gsoff}	Gate-Source Recommended Turn-Off Voltage		-4		V	Static	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	1.8	2.3	3.6	V	$V_{\text{DS}} = V_{\text{GS}}, I_D = 1.86 \text{ mA}$	
			1.9		V	$V_{\text{DS}} = V_{\text{GS}}, I_D = 1.86 \text{ mA}, T_J = 175^\circ\text{C}$	
I_{DSS}	Zero Gate Voltage Drain Current		1	50	μA	$V_{\text{DS}} = 650 \text{ V}, V_{\text{GS}} = 0 \text{ V}$	
I_{GSS}	Gate-Source Leakage Current		10	250	nA	$V_{\text{GS}} = 15 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	
$R_{\text{DS}(\text{on})}$	Drain-Source On-State Resistance		120	160	$\text{m}\Omega$	$V_{\text{GS}} = 15 \text{ V}, I_D = 6.76 \text{ A}$	
			170			$V_{\text{GS}} = 15 \text{ V}, I_D = 6.76 \text{ A}, T_J = 175^\circ\text{C}$	
g_{fs}	Transconductance		5.0		S	$V_{\text{DS}} = 20 \text{ V}, I_{\text{DS}} = 6.76 \text{ A}$	
			4.9			$V_{\text{DS}} = 20 \text{ V}, I_{\text{DS}} = 6.76 \text{ A}, T_J = 175^\circ\text{C}$	
C_{iss}	Input Capacitance		588		pF	$V_{\text{GS}} = 0 \text{ V}, V_{\text{DS}} = 400 \text{ V}$	
C_{oss}	Output Capacitance		45			$F = 1 \text{ Mhz}$	
C_{rss}	Reverse Transfer Capacitance		2.3			$V_{\text{AC}} = 25 \text{ mV}$	
$C_{\text{o(er)}}$	Effective Output Capacitance (Energy Related)		57.5			$V_{\text{GS}} = 0 \text{ V}, V_{\text{DS}} = 0 \text{ V to } 400 \text{ V}$	
$C_{\text{o(tr)}}$	Effective Output Capacitance (Time Related)		80				
E_{oss}	C_{oss} Stored Energy		4.3		μJ	$V_{\text{DS}} = 400 \text{ V}, F = 1 \text{ Mhz}$	
E_{ON}	Turn-On Switching Energy (Body Diode)		35		μJ	$V_{\text{DS}} = 400 \text{ V}, V_{\text{GS}} = -4 \text{ V}/15 \text{ V}, I_D = 6.76 \text{ A}$	
E_{OFF}	Turn Off Switching Energy (Body Diode)		7			$R_{\text{G(ext)}} = 10 \Omega, L = 237 \mu\text{H}, T_J = 175^\circ\text{C}$ FWD = Internal Body Diode of MOSFET	
E_{ON}	Turn-On Switching Energy (External Diode)		29		μJ	$V_{\text{DS}} = 400 \text{ V}, V_{\text{GS}} = -4 \text{ V}/15 \text{ V}, I_D = 6.76 \text{ A}$	
E_{OFF}	Turn Off Switching Energy (External Diode)		7			$R_{\text{G(ext)}} = 10 \Omega, L = 237 \mu\text{H}, T_J = 175^\circ\text{C}$ FWD = External SiC DIODE	
$t_{\text{d(on)}}$	Turn-On Delay Time		8		ns	$V_{\text{DD}} = 400 \text{ V}, V_{\text{GS}} = -4 \text{ V}/15 \text{ V}$ $I_D = 6.76 \text{ A}, R_{\text{G(ext)}} = 10 \Omega$ Timing relative to V_{DS} Inductive load	
t_r	Rise Time		14				
$t_{\text{d(off)}}$	Turn-Off Delay Time		19				
t_f	Fall Time		11				
$R_{\text{G(int)}}$	Internal Gate Resistance		6		Ω	$f = 1 \text{ MHz}, V_{\text{AC}} = 25 \text{ mV}$	
Q_{gs}	Gate to Source Charge		8		nC	$V_{\text{DS}} = 400 \text{ V}, V_{\text{GS}} = -4 \text{ V}/15 \text{ V}$	
Q_{gd}	Gate to Drain Charge		13			$I_D = 6.76 \text{ A}$	
Q_g	Total Gate Charge		26			Per IEC60747-8-4 pg 21	

Note (1): $C_{\text{o(er)}}$, a lumped capacitance that gives same stored energy as C_{oss} while V_{ds} is rising from 0 to 400V

$C_{\text{o(tr)}}$, a lumped capacitance that gives same charging time as C_{oss} while V_{ds} is rising from 0 to 400V



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Reverse Diode Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V_{SD}	Diode Forward Voltage	4.5		V	$V_{GS} = -4 \text{ V}, I_{SD} = 3.4 \text{ A}, T_J = 25^\circ\text{C}$	
		4.0		V	$V_{GS} = -4 \text{ V}, I_{SD} = 3.4 \text{ A}, T_J = 175^\circ\text{C}$	
I_S	Continuous Diode Forward Current		16	A	$V_{GS} = -4 \text{ V}, T_c = 25^\circ\text{C}$	
$I_{S,pulse}$	Diode pulse Current		50	A	$V_{GS} = -4 \text{ V}$, pulse width t_p limited by T_{Jmax}	
t_{rr}	Reverse Recover time	9		ns		
Q_{rr}	Reverse Recovery Charge	133		nC	$V_{GS} = -4 \text{ V}, I_{SD} = 6.76 \text{ A}, V_R = 400 \text{ V}$ $dif/dt = 6245 \text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$	
I_{rrm}	Peak Reverse Recovery Current	22		A		
t_{rr}	Reverse Recover time	16		ns		
Q_{rr}	Reverse Recovery Charge	89		nC	$V_{GS} = -4 \text{ V}, I_{SD} = 6.76 \text{ A}, V_R = 400 \text{ V}$ $dif/dt = 1845 \text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$	
I_{rrm}	Peak Reverse Recovery Current	10		A		

Thermal Characteristics

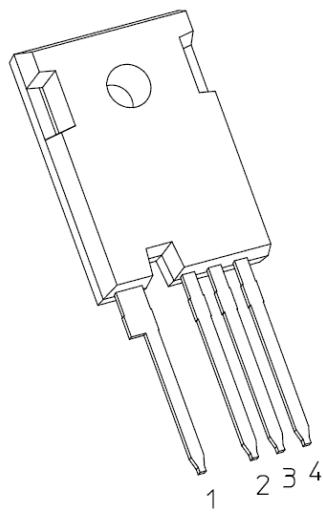
Symbol	Parameter	Typ.	Unit	Test Conditions	Note
$R_{θJC}$	Thermal Resistance from Junction to Case	1.53			
$R_{θJA}$	Thermal Resistance From Junction to Ambient	40	°C/W		



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Package Dimensions



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